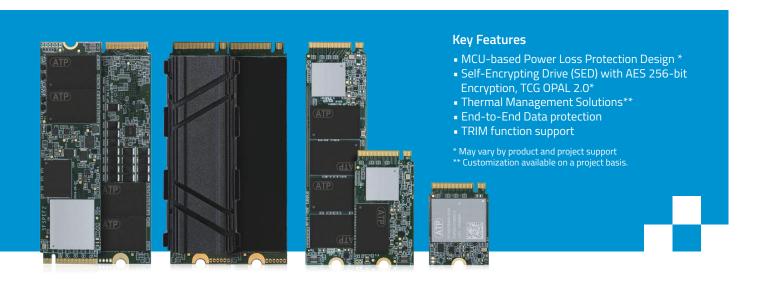


M.2 NVMe

Targeted Product Portfolio, Engineered Specifically for Your Mission Critical Applications



M.2 solid state modules based on the NVMe™protocol leverage the blazing-fast PCI Express® (PCIe®) interface to deliver dramatic improvements in speed and performance to fulfill the increasing demand for responsiveness in enterprise storage systems and to support the growing data-hungry needs of today's enterprise. Delivering 32 Gb/s bandwidth on a PCIe 3.1 x4 slot (8 Gb/s per lane), ATP NVMe SSDs outperform Serial ATA 6 Gb/s SSDs with 4-6X faster access, over 3X lower latency, and higher Input/Output per Second (IOPS). ATP NVMe SSDs with industrial operating temperature rating deliver stable performance even in extreme temperatures ranging from -40°C to 85°C, while Dynamic Thermal Throttling automatically adjusts the speed to maintain cooler operation under intense and heavy workloads.

Adopting NVMe 1.3 specifications and integrating 3D NAND TLC technology, ATP's M.2 2280 NVMe modules offer up to 1.92TB of storage capacity and deliver boosted performance with sequential read up to 3,420 MB/s, sequential write up to 3,050 MB/s, and random read/write IOPS up to 225,200/179,200.

Designed to move past the limitations of mechanical drives, NVMe was specifically built from the ground up for faster, more efficient access to storage devices with non-volatile memory such as current NAND flash solutions and future non-volatile memory technologies. These SSDs can deliver fast, reliable and durable performance for any demanding application.

Specifications

Optional SED Features AES 256-bit Encryption, TCG Opal 2.0 Capacity 40 GB to 320 GB 40 GB to 640 GB 40 GB / 80 GB / 160 GB 120 GB to 960 GB Performance Sequential Read (MB/s) up to 3,150 2,000 3,420 Sequential Write (MB/s) up to 2,670 2,820 1,600 3,050 Random Reads IOPS up to 147,789 (4K, QD32) 135,600 (4K, QD32) 222,700 (4K, QD32) Random Writes IOPS up to 114,227 (4K, QD32) 112,000 (4K, QD32) 176,600 (4K, QD32) Endurance and Reliability Endurance (TBW)² up to 16,000 TB 21,300 TB 4,280 TB 4,640 TB Reliability MTBF @ 25°C >2,000,000 hours >1,500,000 hours >2,000,000 hours Others Dimensions: L x W x H 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA)				M.2 NVMe					
Interface Flash Type									
Fight Type	Product Line	N750Pi	N700Pi	N700Si	N700Sc	N650Si	N650Sc		
Part	Interface			PCIe G3 x4					
Power Loss Power Los P	Flash Type	3D TLC (ps	SLC mode)	3D TLC (ps	SLC mode)	3D 1	ΓLC		
Power Los Protection Options Protection Opti		M.2 2280-D2-M		M.2 2230-S4-M		M.2 2280-D2-M			
Protection Options Planchware Firmware Based Firmware Based Firmware Based Planchware	(Tcase)¹	-40°C t	to 85°C	-40°C to 85°C	0°C to 70°C	-40°C to 85°C	0°C to 70°C		
Capacity		Hardware +	Firmware Based	Firmwar	re Based	Hardware + Firmware Based or Firmware Based			
Sequential Read M/R/si up to Sequential Write Sequential Write M/R/si up to Sequential Write Sequenti	Optional SED Features		AES 256	5-bit Encryption, TCG Opa	al 2.0				
Miss/s up to S	Capacity	40 GB to 320 GB	40 GB to 640 GB		B / 160 GB	120 GB to 960 GB			
MRAS/ up to Random Reads 10PS up to 14.77.89 \		3,150 2,000		00	3,420				
Random Writes iOPS up to 114,227 (kK, QD32) 112,000 (kK, QD32) 176,500 (kK, QD32) 1 10,000 (kK, QD32) 1 1		2,670	2,820	1,600		3,050			
Endurance (TBW)* up to Reliability MTBF @ 25*C Endurance (TBW)* up to Reliability MTBF @ 25*C Endurance (TBW)* up to Sequential Read (MB/s) up to Reliability MTBF @ 25*C Endurance (TBW)* up to Sequential Write (MB)* up to Reliability MTBF @ 25*C Endurance (TBW)* up to Sequential Write (MB)* up to Readown Performance Endurance and Reliability MTBF @ 25*C Endurance (TBW)* up to Reliability MTBF @ 25*C Endurance (TBW)* up to Reliability MTBF @ 25*C Endurance (TBW)* up to Reliability MTBF @ 25*C Endurance and Reliability Endurance Endurance and Reliability Endurance and Reliability Endurance End				135,600	(4K, QD32)	222,700 (4K, QD32)			
Endurance (TBW)* up to 16,000 TB	Random Writes IOPS up to	114,227		112,000 (4K, QD32)		176,600 (4K, QD32)			
Reliability MTBF @ 25°C Dimensions: L x W x So 0.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) So 0.0 x 22.0 x 3.5 (M.2 2280 bare PCBA) So 0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 So 0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) So 0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsi			Eı	ndurance and Reliability					
Dimensions: L x W x H (mm) B0.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) B0.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsind) B0.0 x 22.0 x 2.5 (M.2 22.0 x 3.5 (M.2 2280 with 8 mm heatsind) B0.0		·	·	>1,500,000 hours					
Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 3.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x	Reliability MTBF @ 25°C	>2,000,0	000 hours			>2,000,000 hours			
Certifications				Others			D. D.C.D.A.		
Certifications CE, FCC, BSMI, UKCA, RoHS, REACH 2 years Warranty 5 years 2 years M.2 NIVMe M.2 NIVMe Product Line N600SI N600SC N600Vc				30.0 x 22.0 x 2.5		80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink			
Marranty S y w	, ,						.200 With O Hill Frieddink		
Product Line N600Si N600Sc N600Vc N60						/ears			
Product Line N600Si	•	,				·			
N600Si				M.2 NVMe					
Interface Flash Type 3D TLC 3D	Product Line								
Flash Type	Interface	INPOOR	NPOOSC		NOUVC	NOUVI	NOUVE		
Form Factor M.2 22B		3D	TIC		TLC	3D TLC (TLC Mode)			
Operating Temperature (Tcase)¹ -40°C to 85°C 0°C to 70°C 0°C to 70°C -40°C to 85°C 0°C to 70°C Power Loss Protection Options Optional SED Features Hardware + Firmware Based or Firm Based or Firmware Based or Fi	**								
Power Loss Protection Options Power Loss Protection Options Power Loss Protection Options Power Loss Protection Options Partwers Parts									
Protection Options Hardware + Firmware Based or Firmware Based Firmware Based Optional SED Features AES 256-bit Encryption, TCG Opal 2.0 - Capacity 120 GB to 1,920 GB 120 GB to 960 GB 120 GB / 240 GB / 480 GB Performance Sequential Read (MB/s) up to 3,420 2,600 2,000 Sequential Write (MB/s) up to 3,050 1,870 1,570 Random Reads IOPS up to 225,200 (4K, QD32) 184,300 (4K, QD32) 135,600 (4K, QD32) Random Writes IOPS up to 179,200 (4K, QD32) 145,900 (4K, QD32) 112,000 (4K, QD32) Endurance (TBW)² up to 5,585 TB 1,536 TB 768 TB Reliability MTBF @ 25 °C >2,000,000 hours >2,000,000 hours >1,536 TB 768 TB Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5		-40°C to 85°C	0°C to 70°C	0°C to	o 70°C	-40°C to 85°C	0°C to 70°C		
Capacity 120 GB to 1,920 GB 120 GB to 960 GB 120 GB / 240 GB / 480 GB Performance Sequential Read (MB/s) up to 3,420 2,600 2,000 Sequential Write (MB/s) up to 3,050 1,870 1,570 Random Reads IOPS up to 225,200 (4K, QD32) 184,300 (4K, QD32) 135,600 (4K, QD32) Random Writes IOPS up to 179,200 (4K, QD32) 145,900 (4K, QD32) 112,000 (4K, QD32) Endurance (TBW)² up to 5,585 TB 1,536 TB 768 TB Reliability MTBF @ 25 °C > 2,000,000 hours > 2,000,000 hours > 2,000,000 hours > 1,500,000 hours Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5		Hardware + Firmware B	ased or Firmware Based	Firmware Based					
Sequential Read (MB/s) up to 3,420 2,600 2,000 2,000	Optional SED Features	AES 256-bit Encr	ryption, TCG Opal 2.0			-			
Sequential Read (MB/s) up to 3,420 2,600 2,000 Sequential Write (MB/s) up to 3,050 1,870 1,570 Random Reads IOPS up to 225,200 (4K, QD32) 184,300 (4K, QD32) 135,600 (4K, QD32) Random Writes IOPS up to 179,200 (4K, QD32) 145,900 (4K, QD32) 112,000 (4K, QD32) Endurance (TBW)² up to 5,585 TB 1,576 768 TB Reliability MTBF @ 25°C >2,000,000 hours >2,000,000 hours >1,500,000 hours Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5	Capacity	120 GB to 1,920 GB		120 GB t	o 960 GB	120GB / 240GB / 480GB			
(MB/s) up to 3,420 2,600 Sequential Write (MB/s) up to 3,050 1,870 1,570 Random Reads IOPS up to 225,200 (4K, QD32) 184,300 (4K, QD32) 135,600 (4K, QD32) Random Writes IOPS up to 179,200 (4K, QD32) 145,900 (4K, QD32) 112,000 (4K, QD32) Endurance (TBW)² up to 5,585 TB 1,536 TB 768 TB Reliability MTBF @ 25°C >2,000,000 hours >2,000,000 hours >1,500,000 hours Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5				Performance					
(MB/s) up to 3,050 1,870 Random Reads IOPS up to 225,200 (4K, QD32) 184,300 (4K, QD32) 135,600 (4K, QD32) Random Writes IOPS up to 179,200 (4K, QD32) 145,900 (4K, QD32) 112,000 (4K, QD32) Endurance (TBW)² up to 5,585 TB 1,536 TB 768 TB Reliability MTBF @ 25°C >2,000,000 hours >2,000,000 hours >1,500,000 hours Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5	(MB/s) up to	3,420		2,600		2,000			
Random Writes IOPS up to 179,200 (4K, QD32) 145,900 (4K, QD32) 112,000 (4K, QD32) Endurance and Reliability Endurance (TBW)² up to 5,585 TB 1,536 TB 768 TB Reliability MTBF @ 25°C >2,000,000 hours >1,500,000 hours >1,500,000 hours Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5	•	3,050							
Endurance and Reliability Endurance (TBW)² up to 5,585 TB 1,536 TB 768 TB Reliability MTBF @ 25°C >2,000,000 hours >1,500,000 hours >1,500,000 hours Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5	Random Reads IOPS up to			, , , , ,					
Endurance (TBW)² up to	Random Writes IOPS up to	179,20			4K, QD32)	112,000	(4K, QD32)		
Reliability MTBF @ 25°C >2,000,000 hours >2,000,000 hours >1,500,000 hours Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 22.0 x 2.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.2 42.0 x 22.0 x 3.6 30.0 x 22.0 x 2.5			Er	ndurance and Reliability					
Others Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.5 30.0 x 22.0 x 2.5		·							
Dimensions: L x W x H (mm) 80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink) 80.0 x 22.0 x 2.5 42.0 x 22.0 x 3.6	Reliability MTBF @ 25°C	>2,000,0	>2,000,000 hours >2,000,000 hours >1,500,000 hours			,000 hours			
(mm) 80.0 x 24.4 x 12.5 (M.2 2280 WILL 8 THITH HEALSHIK)					42.0 x 22.0 x 3.6	30.0 x 3	22.0 x 2.5		
	· · ·	80.0 x 24.4 x 12.5 (M.2 2				33.0 X 2			

¹ Case Temperature, the composite temperature as indicated by SMART temperature attributes. 2 Under highest Sequential write value. May vary by density, configuration and applications.

Technologies & Add-On Services	S.M.A.R.T.	Hardware-based Power Loss Protection	AutoRefresh	Advanced Wear Leveling	Dynamic Data Refresh	End-to End Data Protection	Secure Erase	P TCG Opal 2.0	Signification industrial Temperature	Anti-Sulfur Resistors	Conformal Coating
Premium	0	0	0	0	0	0	A	0	0	A	A
Superior	0	0	0	0	0	0	A	0	A	A	A
Value	0	0	0	0	0	0	-	-	-	A	A

2 years

Warranty

 $[\]blacktriangle$: Customization option available on a project basis.

Hot Items Ordering Information								
Product Line	Capacity₁	Operating Temperature ₂	Power Loss Protection ₃	SED ₄	P/N			
N650Si	120GB	-40°C to 85°C	Hardware + Firmware Based	-	AF120GSTJA-8BCIP			
N650Si	240GB	-40°C to 85°C	Hardware + Firmware Based	-	AF240GSTJA-8BCIP			
N650Si	480GB	-40°C to 85°C	Hardware + Firmware Based	-	AF480GSTJA-8BCIP			
N650Si	960GB	-40°C to 85°C	Hardware + Firmware Based	-	AF960GSTJA-8BCIP			
N650Sc	120GB	0°C to 70°C	Hardware + Firmware Based	-	AF120GSTJA-8BCXP			
N650Sc	240GB	0°C to 70°C	Hardware + Firmware Based	-	AF240GSTJA-8BCXP			
N650Sc	480GB	0°C to 70°C	Hardware + Firmware Based	-	AF480GSTJA-8BCXP			
N650Sc	960GB	0°C to 70°C	Hardware + Firmware Based	-	AF960GSTJA-8BCXP			
N600Sc	120GB	0°C to 70°C	Hardware + Firmware Based	-	AF120GSTJA-8BAXP			
N600Sc	240GB	0°C to 70°C	Hardware + Firmware Based	-	AF240GSTJA-8BAXP			
N600Sc	480GB	0°C to 70°C	Hardware + Firmware Based	-	AF480GSTJA-8BAXP			
N600Sc	960GB	0°C to 70°C	Hardware + Firmware Based	-	AF960GSTJA-8BAXP			
N600Sc	1920GB	0°C to 70°C	Hardware + Firmware Based	-	AF1T92STJA-8BAXP			
N600Sc	120GB	0°C to 70°C	Firmware Based	-	AF120GSTJA-8BAXX			
N600Sc	240GB	0°C to 70°C	Firmware Based	-	AF240GSTJA-8BAXX			
N600Sc	480GB	0°C to 70°C	Firmware Based	-	AF480GSTJA-8BAXX			
N600Sc	960GB	0°C to 70°C	Firmware Based	-	AF960GSTJA-8BAXX			
N600Sc	1920GB	0°C to 70°C	Firmware Based	-	AF1T92STJA-8BAXX			
N600Vc (M.2 NVMe 2280)	120GB	0°C to 70°C	Firmware Based	-	AF120GSTJA-DBCXX			
N600Vc (M.2 NVMe 2280)	240GB	0°C to 70°C	Firmware Based	-	AF240GSTJA-DBCXX			
N600Vc (M.2 NVMe 2280)	480GB	0°C to 70°C	Firmware Based	-	AF480GSTJA-DBCXX			
N600Vc (M.2 NVMe 2242)	120GB	0°C to 70°C	Firmware Based	-	AF120GSTJC-DBBXX			
N600Vc (M.2 NVMe 2242)	240GB	0°C to 70°C	Firmware Based	-	AF240GSTJC-DBBXX			
N600Vc (M.2 NVMe 2242)	480GB	0°C to 70°C	Firmware Based	-	AF480GSTJC-DBBXX			
N600Vc (M.2 NVMe 2242)	960GB	0°C to 70°C	Firmware Based	-	AF960GSTJC-DBBXX			

¹ Amount of actual usable storage that can be utilized.

Product spec and its related information are subject to change without advance notice. Please refer to <u>www.atpinc.com</u> for latest information

v2 202207

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The Global Leader in Specialized Storage and Memory Solutions

 $^{{\}tt 2~Refers~to~Case~Temperature~range~during~device~operation,~as~indicated~by~SMART~temperature~attributes.}\\$

³ Hardware + Firmware-based power loss protection design with Level 4 (data-in-flight) protection; Firmware-based power loss protection design with Level 1 (data-at-rest) protection.

4 Allows data written to and read from the SSD to be constantly and automatically encrypted and decrypted. Conforms to TCG Opal 2.0 and uses AES 256-bit HW encryption.